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A ceramic electronic component includes: a body including dielectric layers and internal electrodes; and external electrodes disposed on the body and connected to the internal electrodes, in which the dielectric layers include a plurality of dielectric crystal grains, an average number of dielectric crystal grains per unit thickness ($1\ \mu\text{m}$) of the dielectric layers is 8 or more, and t_d is $0.5\ \mu\text{m}$ or less, t_d being an average thickness of at least one of the dielectric layers.

